

# Specification of Thermoelectric Module

## TEC1-24108P

### Description

The 241 couples, 54.4 mm × 54.4/57.0 mm size module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 70 °C, designed for superior cooling and heating up to 100 °C /200°C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

### Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

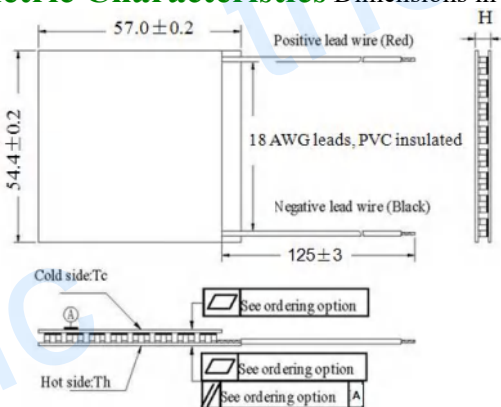
### Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

### Performance Specification Sheet

Th(°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>
DT <sub>max</sub> (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U <sub>max</sub> (Voltage)	30.0	32.4	Voltage applied to the module at DT <sub>max</sub>
I <sub>max</sub> (amps)	8.3	8.3	DC current through the modules at DT <sub>max</sub>
Q <sub>Cmax</sub> (Watts)	159.7	172.0	Cooling capacity at cold side of the module under DT=0 °C
AC resistance(ohms)	2.75	2.95	The module resistance is tested under AC
Tolerance (%)	± 10		For thermal and electricity parameters

### Geometric Characteristics Dimensions in millimeters



### Ordering Option

Suffix	Thickness (mm)	Flatness/Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0:3.4±0.1	0:0.1/0.1	125±3/Specify
TF	1:3.4±0.05	1:0.05/0.05	125±3/Specify

Eg. TF01: Thickness 3.4 ± 0.1 (mm) and Flatness 0.05 / 0.05 (mm)

### Manufacturing Options

#### A. Solder:

1. T100: BiSn (Tmelt=138°C)
2. T200: CuAgSn (Tmelt = 217°C)
3. T240: SbSn (Tmelt = 240°C)

#### B. Sealant:

1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant

#### C. Ceramics:

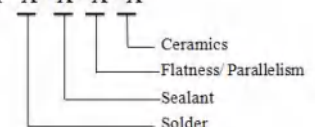
1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)
2. Aluminum Nitride (AlN)

#### D. Ceramics Surface Options:

1. Blank ceramics (not metalized)
2. Metalized

### Naming for the Module

TEC1- 24108P- X - X - X - X



TEC1- 24108P- T200 -NS - TF01 - AlO

T200: Solder, CuSn (Melting Point=227 °C)

NS: No sealing

AlO: Alumina white 96%

TF01: Thickness ± 0.1(mm) and Flatness/Parallelism 0.05/0.05(mm)

Creative technology with fine manufacturing processes provides you the reliable and quality products.

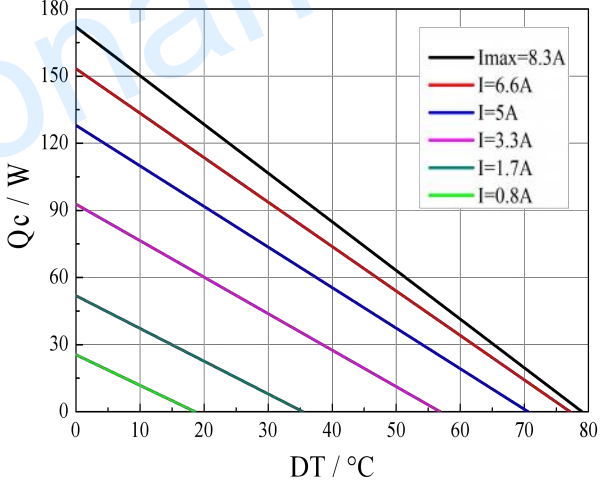
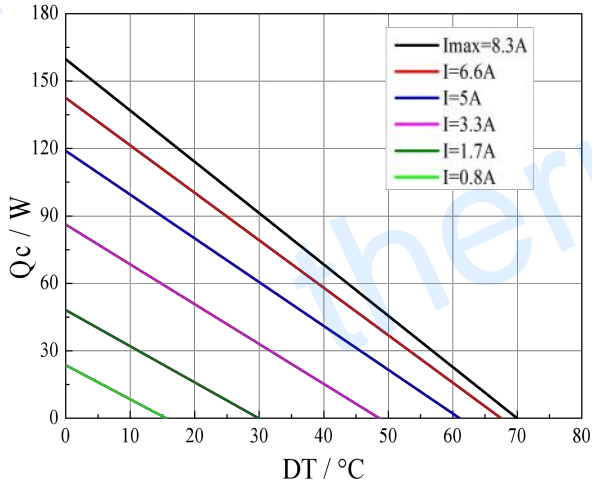
Tel: +86-791-88198288 Fax: +86-791-88198308 Email: [sales@thermonamic.com.cn](mailto:sales@thermonamic.com.cn) Web Site: [www.thermonamic.com.cn](http://www.thermonamic.com.cn)

# Specification of Thermoelectric Module

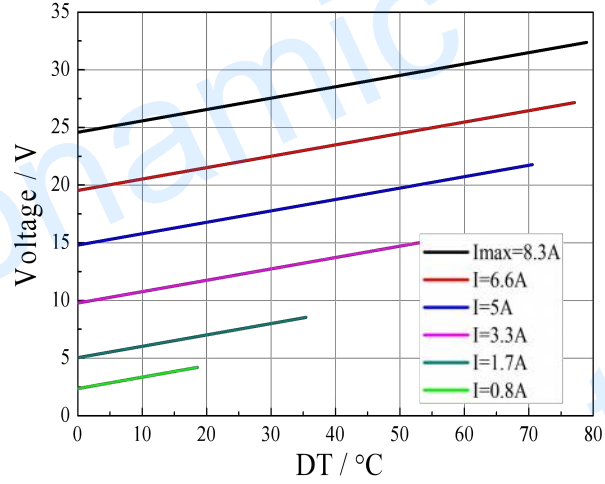
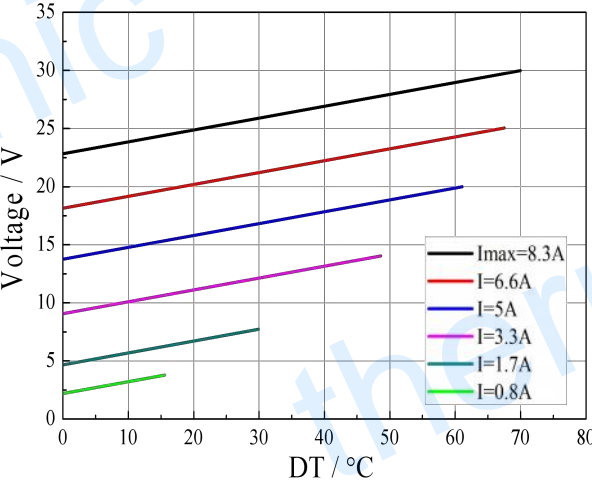
## TEC1-24108P

**Performance Curves at Th=27 °C**

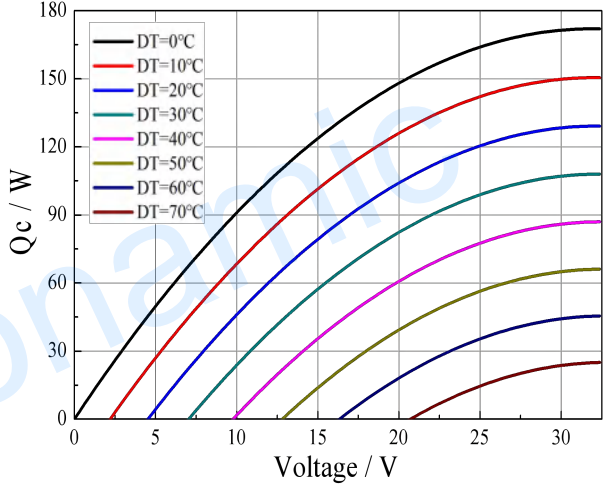
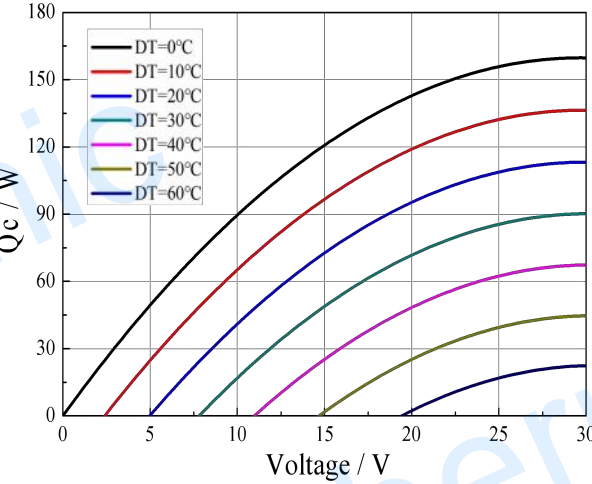
**Performance Curves at Th=50 °C**



Standard Performance Graph  $Q_c = f(DT)$



Standard Performance Graph  $V = f(\Delta T)$

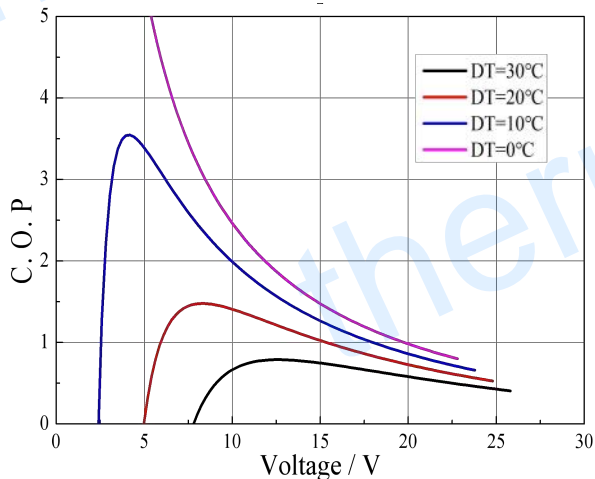


Standard Performance Graph  $Q_c = f(V)$

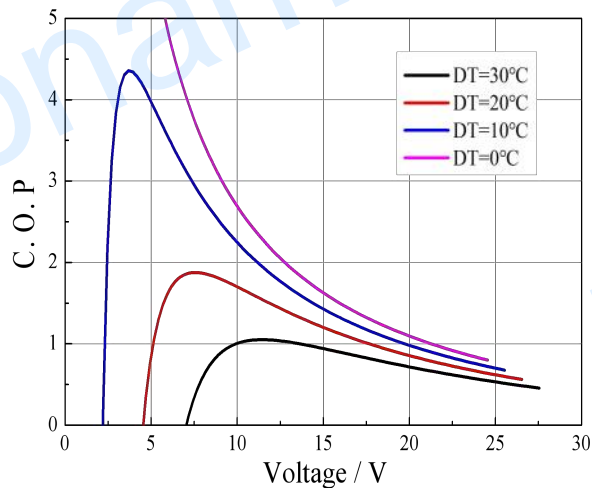
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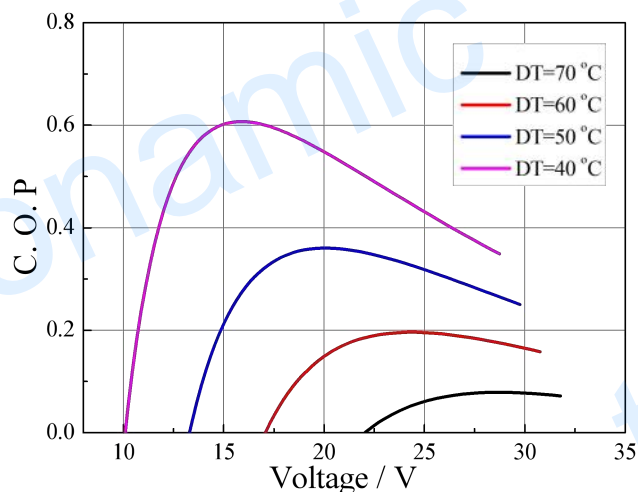
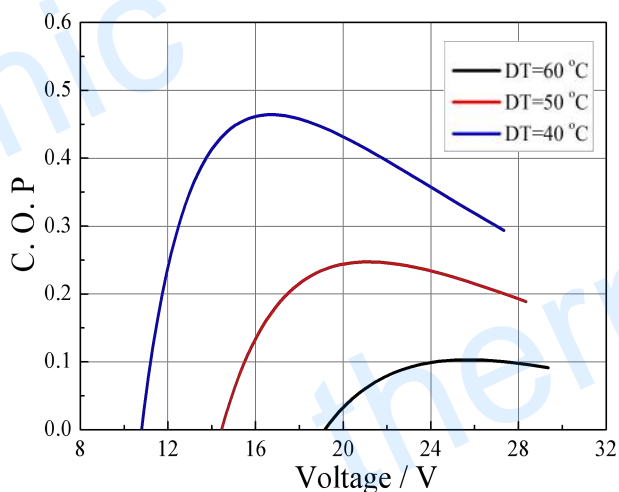
#### Performance Curves at Th=27 °C



#### Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of ΔT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of ΔT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power  $Q_c$ /Input power ( $V \times I$ ).

### Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating.
- Operation or storage module below 100 °C
- Operation below  $I_{max}$  or  $V_{max}$
- Work under DC